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Form PTO 1400 INFORMATION DISCLOSURE CITATION				Attorney Docket No. S243 1020.1			Serial No. 10/053,859			
				Applicant Goodson, et al.						
	(Use several sheets if necessary)				Filing Date 01/19/02			Group 3743		
			U.S.	PATENT DOCU	JMENTS					
Examiner Initials	Item	Document Number	Date	Name		Class	Subclass		Filing Date If Appropriate	
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Subclass Translation Document Date Country Class Number Yes No OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.) AKA Laminar flow through microchannels used for microscale cooling systems", Jiang et al., Proceedings of the Electronic Technology Conference, EPTC; 1997; p.119-122 AKB 'Fabrication of monolithic microchanriels for IC chip cooling", Joo et al., Proceedings of the IEEE Micro Electro Mechanical Systems; 1995; p.362-367 AKC'Performance test and analysis of silicon-based microchannel heat sink", Kang et al, Proceedings of SPIE - The International Society for Optical Engineering; 1999; v.3795, p.259-270 AKD Micro heat exchangers consisting of pin arrays", Yin, et al., Journal of Electronic Packaging, Mar. 1996, v.118, p.51-57 AKE "Measurements of Heat Transfer in Microchannel Heat Sinks", Rahman, International Communications in Heat and Mass Transfer, May 2000, v.27, no.4, p.495-506 AKF "Enhancement of Critical Heat Flux From High Power Microelectronic Heat Sources in a Flow Channel", Mudawar, et

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

AKG' Closed-Loop Electroosmotic Microchannel Cooling System for VLSI Circuits", Jiang, et at., printed in Journal of

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AKHI'Liquid Flows in Microchannels", Sharp, et al., CRC Press, 2002, Chapter 6, p.6-1 to 6-38

at., Journal of Electronic Packaging, Sept. 1990, v.132, p.241-248

MEMS, Jan. 2002

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		OTHER DOCUM	ENTS	(Including Author, I	itle, Date, Pert	inent Pa	ges,	etc.)		;
m		ALA "Fabrication and characterization of electrokinetic micro pumps", Zeng, et al., 2000 Inter Society Conference on Thermal Phenomena, May 2000, p.31 -35								
M		LB "Thermal-hydraulic characteristic of micro heat exchangers", Wang, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1991, v.32, p.331-339								
M	ALC "Electrokinetic Generation of High Pressures Using Porous Microstructures", Paul, et at., Micro-total analysis systems, 1998, Banff, Canada 1998, p.49-52									
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